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## Product Change Notification - JAON-29SXBX512

**Date:** 06 Dec 2016  
**Product Category:** Supertex  
**Notification subject:** CCB 2773 Initial Notice: Qualification of GTBF assembly site for selected Supertex products available in 3L DPAK package using 8060T die attach material.  
**Notification text:** **PCN Status:**  
 Initial notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of GTBF assembly site for selected Supertex products available in 3L DPAK package using 8060T die attach material.

**Pre Change:**

Assembled at GEMC assembly site using 84-1LMISR4 die attach material

**Post Change:**

Assembled at GTBF assembly site using 8060T die attach material

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	GEMC	GTBF
<b>Wire material</b>	Au wire	Au wire
<b>Die attach material</b>	84-1LMISR4	8060T
<b>Molding compound material</b>	G600	G600
<b>Lead frame material</b>	PMC90	PMC90

**Impacts to Data Sheet:**  
None

**Change Impact:**  
None

**Reason for Change:**  
To improve on-time delivery performance by qualifying GTBF assembly site.

**Change Implementation Status:**  
In Progress

**Estimated Qualification Completion Date:**  
March 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

**Time Table Summary:**

	December 2016					->	March 2017				
Workweek	48	49	50	51	52		09	10	11	12	13
Initial PCN Issue Date		X									
Qual Report Availability									X		
Final PCN Issue Date									X		

**Method to Identify Change:**  
Traceability code

**Qualification Plan:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

**Revision History:**  
**December 6, 2016:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-29SXBX512\\_Qual Plan.pdf](#)  
[PCN\\_JAON-29SXBX512\\_Affected CPN.pdf](#)  
[PCN\\_JAON-29SXBX512\\_Affected CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29SXBX512
CATALOG_PART_NBR
DN2450K4-G
DN2470K4-G
DN2625K4-G
DN3765K4-G
GN2470K4-G
TN2640K4-G